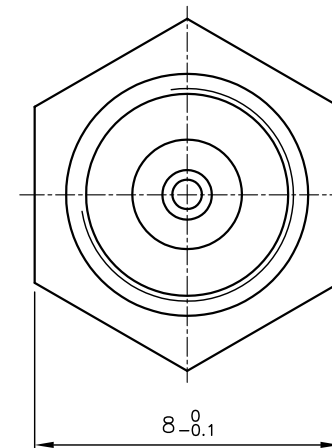
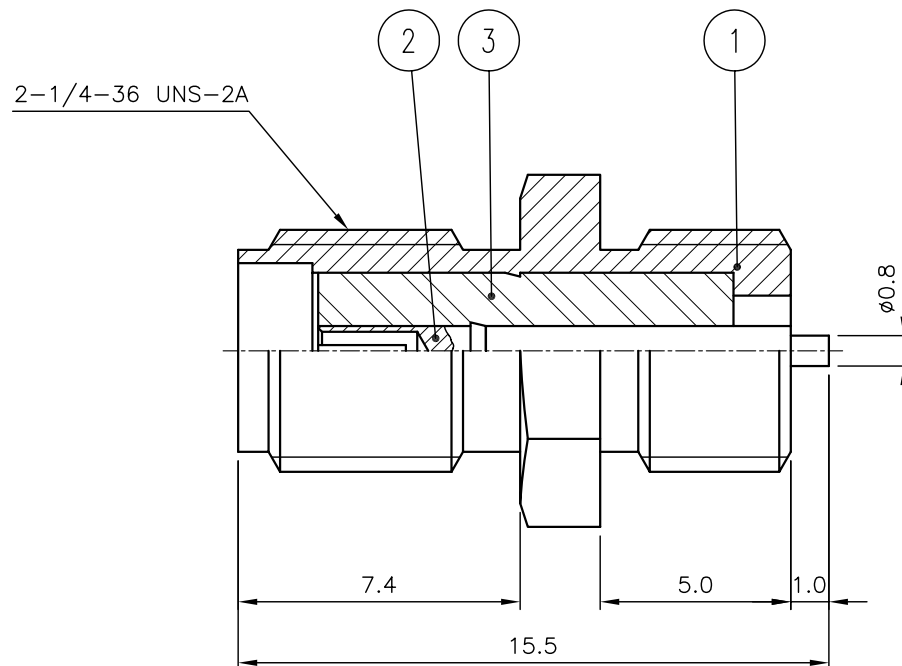


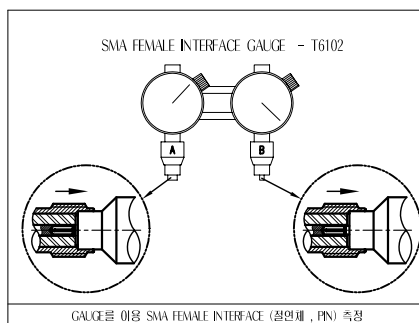
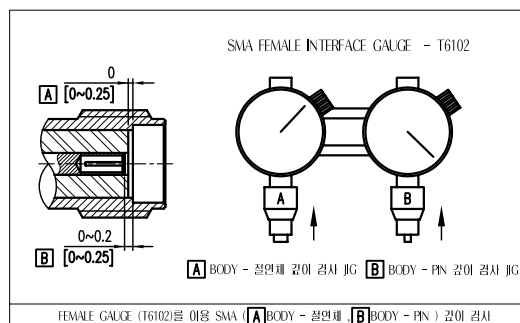
REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	I.C.KIM	Y.H.CHOI	2011.04.27.
↑	[설번처리No.201105-0002] 절연체 밀림 방지 BODY 내부 구조 변경	I.C.KIM	Y.H.CHOI	2011.05.16.



주 기

1. KJ CODE - ZE00012-N/1 JIG 사용하여 조립 할 것.

※2. Aeroflex / PD00332-7/1 제품 적용시 BODY + CASE 도장후
절연체, PIN 조립 진행 할 것



** PIN 높이 검사 방법 **

3	INSULATOR	1	TEFLON		DIN01916-N/1 DIN01909-N/1
2	CONTACT	1	BeCu	Gold Plate	DCT02459-5/1 DCT02442-5/1
1	BODY	1	SUS	부동태 처리	DBD02925-5/1 DBD00343-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2011. 05. 16.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	Y.H.CHOI	
MATERIAL		CHECKED BY		KJ COMTECH CO.,LTD. TITLE SMA50 SOLDER END JB (F/F)
		DRAWN BY	I.C.KIM	
FINISH		SCALE	5/1	DWG NO. CN02677-7/1 REVISION 1 SHEET 1 of 1
		UNIT	mm	